YETDA INDUSTRY LTD.

0.39” SINGLE DIGIT RED LED DISPLAY

T-3932AR11

DESCRIPTION

*Triple Digit, 0.39” Inch Digit Height.

* Deep Red Color Display.

* Black Face and White Segment Color.

* Common Anode.

ABSOLUT MAXIMUM RATINGS AT Ta=25°C

Parameter		UNIT
Power Dissipation	72	mW
Peak Forward Current	100	mA
Forward current	20	mA
Reverse Voltage	5	V
Operation Temperature Range	-25°C TO +80°C	°C
Storage Temperature Range	-25°C TO +100°C	°C
Lead Soldering Temperature	260℃ for 3 seconds 1.6mm(1/16 inch) from body	

ELECTRICAL/OPTOTICAL CHARACTERISTIC AT Ta=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Average Luminous Intensity	Iv	300		800	ucd	If=1mA
Peak Emission Wavelength	λ d	630		640	nm	If=20mA
Forward Voltage Per Seg.	Vf		2.2		V	If=20mA
Reverse Current Per Seg.	Ir			10	uA	Vr=5V
Luminous Intensity Matching Ratio	Iv-m	2 : 1				If=20mA

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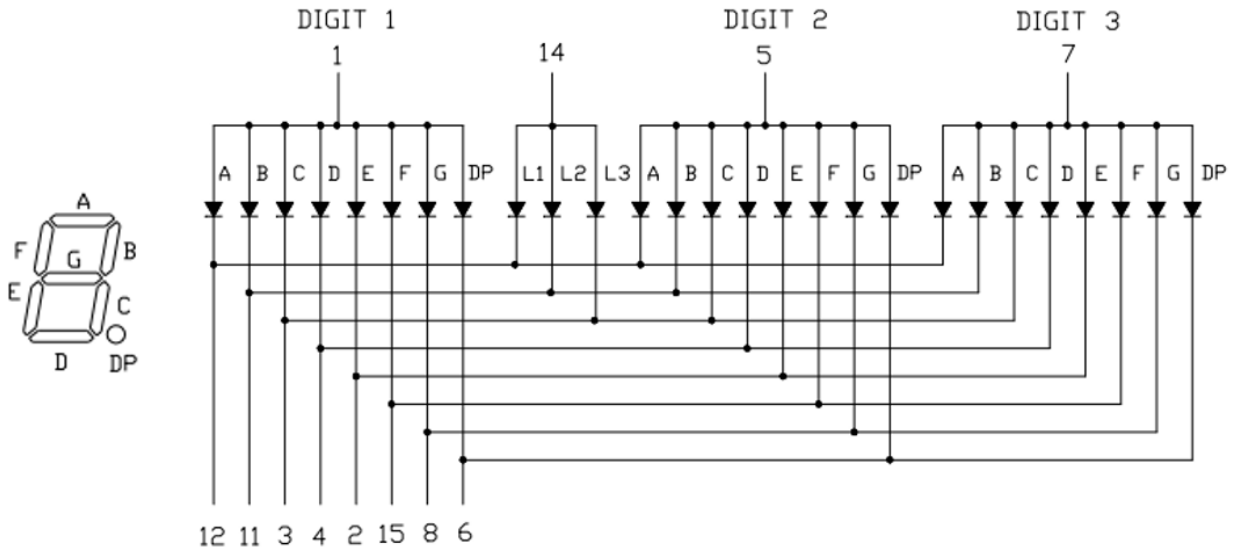
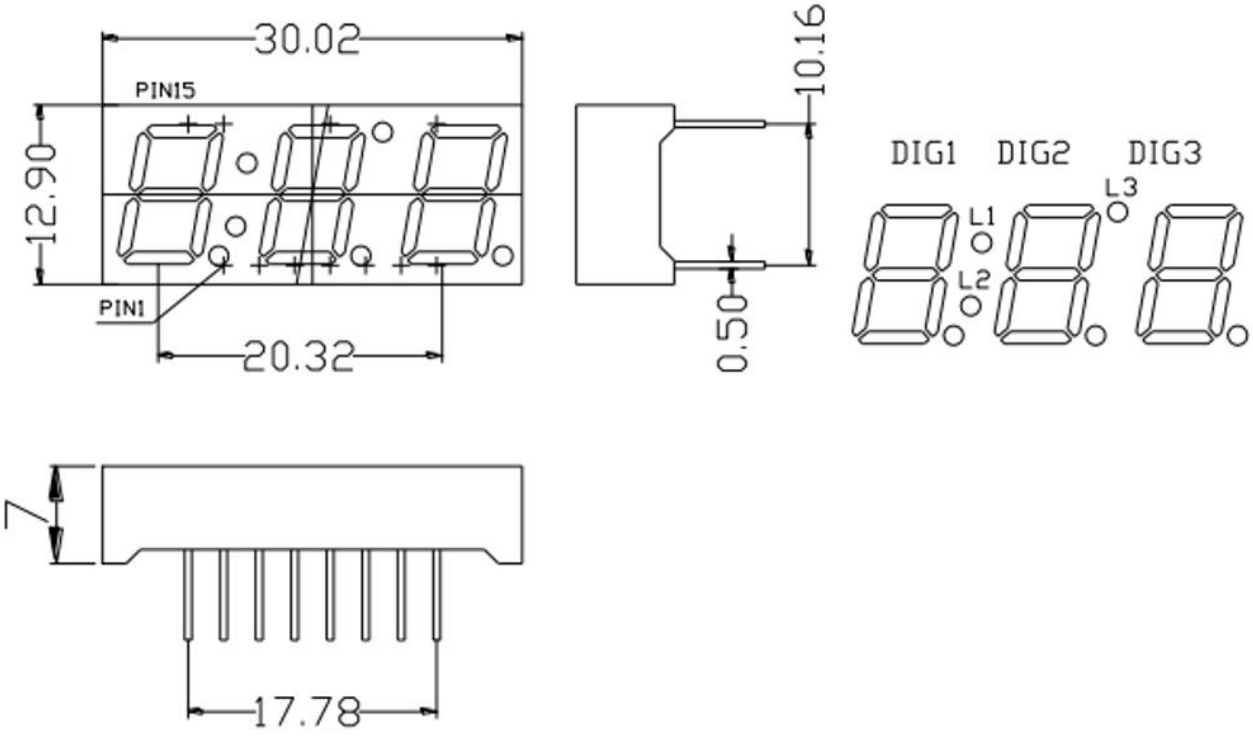
P.C.B. Pin Connection



Reflector Dimensions



Notes:（备注）

1. All dimension units are millimeters.（所有标注尺寸单位为毫米）

2.All dimension tolerance is ±0.15mm unless otherwise noted.（除特别标注外，所有尺寸允许公差±0.15㎜ ）

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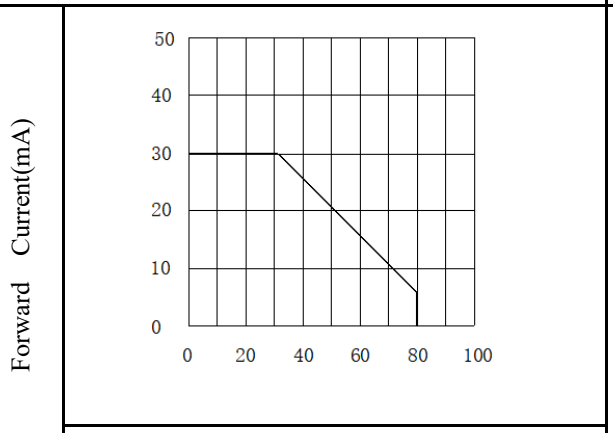
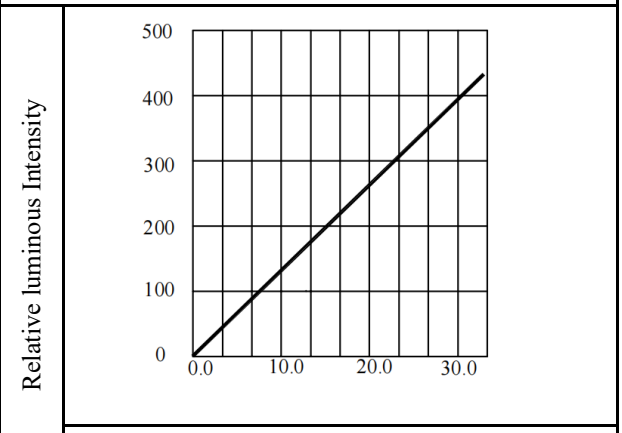
Typical optical characteristics curves　典型光学特性曲线

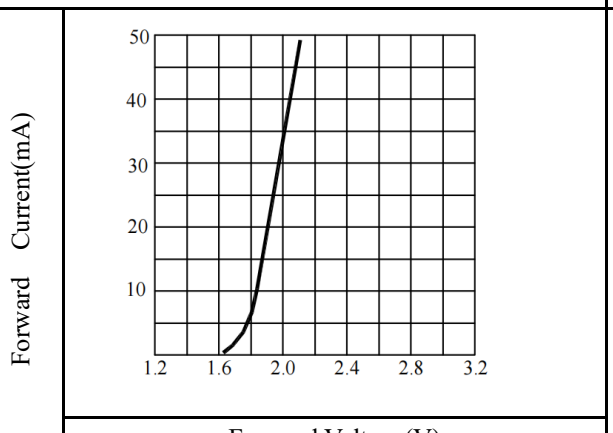
Ambient Temperature vs. Forward Current
环境温度与正向电流特性曲线



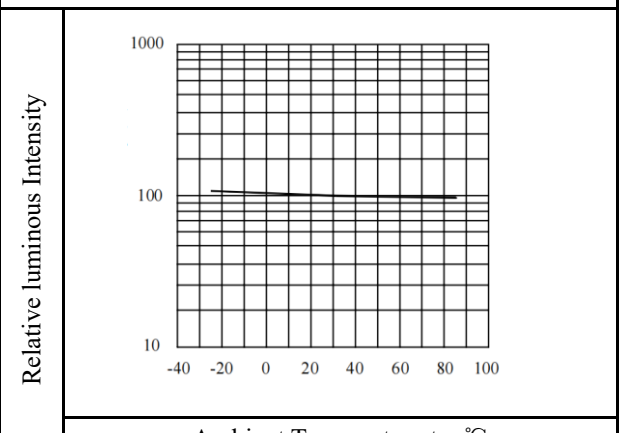
Forward Current VS. Relative Intensity
正向电流与相对光强特性曲线



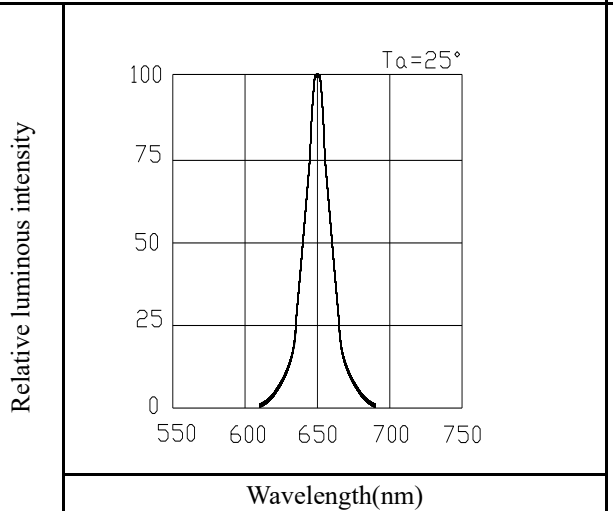
Forward Voltage VS. Forward Current
正向电压与正向电流特性曲线



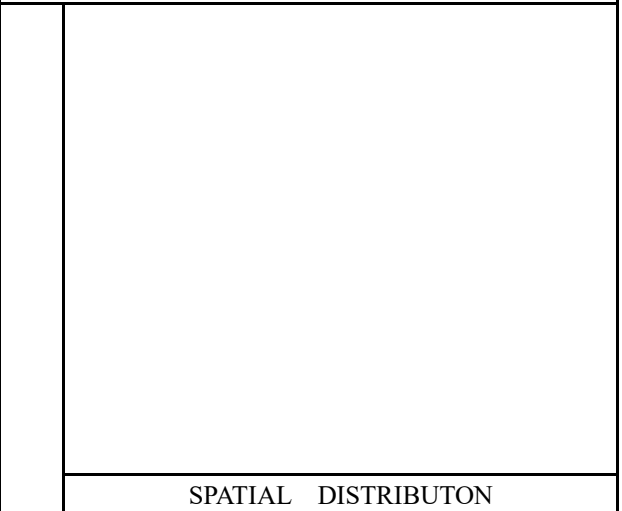
Ambient Temperature VS. Relative Intensity
环境温度与相对光强特性曲线



Relative spectral emission
相对光谱分布特性曲线



Radiation diagram
辐射图特性曲线



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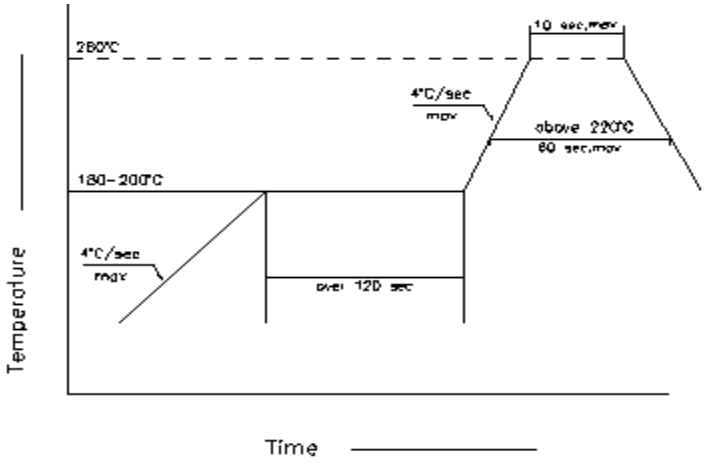
U.S.L: Upper Specification Limit 规格上限　　L.S.L: Lower Specification Limit　规格下限

*The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

数据工作表中所示的技术信息仅限于典型特征和电路实例引用的产品. 它既不构成工业特性的保证, 也不构成任何许可的授权.

SMT Reflow Soldering Instructions　SMT 回流焊说明



1.Reflow soldering should not be done more than two times.　回流焊不可以做两次以上

2.When　soldering , do not put stress on the LEDs during heating

当焊接时，不要在材料受热时用力压胶体表面

Soldering iron　烙铁焊接

1.When hand soldering, keep the temperature of　iron below less 300℃ less than 3 seconds

当手工焊接时，烙铁的温度必须小于 300℃，时间不可超过 3 秒

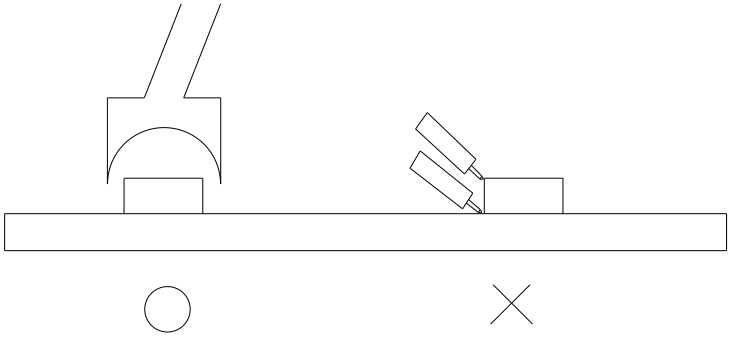
2.The hand solder should be done only one times

手工焊接只可焊接一次

Repairing　修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED 回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏 LED 本身的特性。



Cautions　注意事项

5.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material.

LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM

6.When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine element is required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external glue of the application products is required to be less than 1500PPM

当我们需要使用外封胶涂抹 LED 产品时，应确保外封胶与 LED 封装胶水相匹配，因为大多数 LED 的封装胶水为硅胶，它有较强的氧化性和较强的吸湿性，必须防止外封材质进入 LED 内部以造成 LED 的损伤，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，在涂抹 LED 产品时要求外封胶溴元素与氯元素总含量必须小于 1500PPM

7.Other points for attention, please refer to our LED user manual.

其它注意事项请参照我们的 LED 使用手册